Tecnite®

innovative solutions

THERMAL PAD - DT50

Features

- Thermal conductivity: 5.0 W/mK
- High conformability
- Cost effective solution
- Electrically insulating
- Naturally sticky
- High dielectric breakdown of up to 6.0 kV/mm
- Custom die-cut parts: custom configurations available



Applications

- Between electronic components: semiconductors, ICs, CPUs, MOS and heasink
- LEDs, LCD TV, telecom devices, wireless hubs, PCs, power supply etc.
- Cooling and thermal modules
- In all applications where a metal housing is used as heatsink.

Reach RoHS Compliant Underwriters Laboratories

TECNITE DT50

Properties	Unit	DT50	Test Method
Composition		Silicone & ceramic filled	
Colour		Grey red	
Thickness range	mm	0.5 -5.0	
Hardness	Shore C	40	ASTM D2240
Density	g/ml	3.5	ASTM D792
Elongation	%	80	ASTM D412
Temperature range	°C	-40 to 150	EN344
Breakdown voltage	kV/mm	≥6.0	ASTM D149
Volume impedance	ohm*cm	$1.1*10^{16}$	ASTM D257
Dielectric constant	@ 1 MHz	6.4	ASTM D150
Weight damnify	%	≤0.5	@ 150 °C 240H
Thermal conductivity	W/mK	5.0	ASTM D5470
Compliances		UL 94 V-0, RoHS, REACH	
Sheet sizes		Standard: 200*400 mm	
Custom configurations		Custom die-cut parts available. Available with acrylic PSA tape for improved application on one or both sides: • 3M Double Coated Tape 9448HK (will make the pad 0.15 mm thicker on both sides) • 3M Transfer Tape 3M467 (will make the pad 0.06 mm thicker on both sides)	

DISTRIBUTORS GROUP EUROPE
Handelsweg 6, NL - 2404 CD Alphen aan den Rijn, The Netherlands
Tel. 0031-172-436361 Fax 0031-172-420310
info@dge-europe.com www.dge-europe.com